

# **JFET Chopper**

P-Channel - Depletion

# MMBFJ177LT1G, SMMBFJ177LT1G

### **Features**

- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant



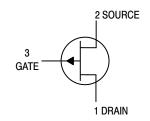
Rating	Symbol	Value	Unit
Drain-Gate Voltage	$V_{DG}$	-25	Vdc
Gate-Source Voltage	V <sub>GS</sub>	25	Vdc

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

## THERMAL CHARACTERISTICS

Total Device Dissipation FR-5 Board (Note 1)	P <sub>D</sub>	225	mW
T <sub>A</sub> = 25°C Derate above 25°C		1.8	mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

<sup>1.</sup> FR-5 =  $1.0 \times 0.75 \times 0.062$  in.





SOT-23 (TO-236) CASE 318-08 STYLE 10

### **MARKING DIAGRAM**



6Y = Specific Device Code

M = Date Code\*

= Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation and/or overbar may vary depending upon manufacturing location.

## **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MMBFJ177LT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel
SMMBFJ177LT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## MMBFJ177LT1G, SMMBFJ177LT1G

## **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Max	Unit		
OFF CHARACTERISTICS							
Gate-Source Breakdown Voltage (V <sub>DS</sub> =	V <sub>(BR)GSS</sub>	30	-	Vdc			
Gate Reverse Current (V <sub>DS</sub> = 0 Vdc, V <sub>GS</sub> = 20 Vdc)		I <sub>GSS</sub>	-	1.0	nAdc		
Gate Source Cutoff Voltage (V <sub>DS</sub> = -15 Vdc, I <sub>D</sub> = -10 nAdc)		Gate Source Cutoff Voltage (V <sub>DS</sub> = -15 Vdc, I <sub>D</sub> = -10 nAdc)		V <sub>GS(off)</sub>	0.8	2.5	Vdc
ON CHARACTERISTICS							
Zero-Gate-Voltage Drain Current (V <sub>GS</sub> = 0, V <sub>DS</sub> = -15 Vdc) (Note 2)		I <sub>DSS</sub>	-1.5	-20	mAdc		
Drain Cutoff Current (V <sub>DS</sub> = -15 Vdc, V <sub>GS</sub> = 10 Vdc)		I <sub>D(off)</sub>	=	-1.0	nAdc		
Drain Source On Resistance (I <sub>D</sub> = –500 μAdc)		r <sub>DS(on)</sub>	=	300	Ω		
Input Capacitance	V <sub>DS</sub> = 0, V <sub>GS</sub> = 10 Vdc	C <sub>iss</sub>	-	11	pF		
Reverse Transfer Capacitance	f = 1.0 MHz	C <sub>rss</sub>	-	5.5	1		

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

## **TYPICAL CHARACTERISTICS**

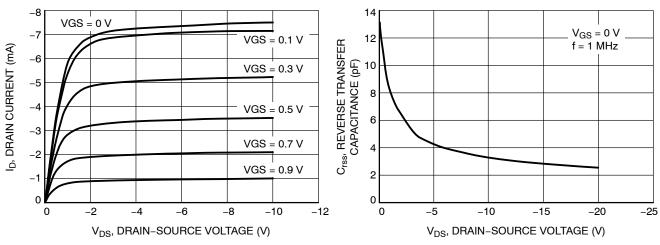


Figure 1. Drain Current vs. Drain-Source Voltage

Figure 2. Reverse Transfer Capacitance

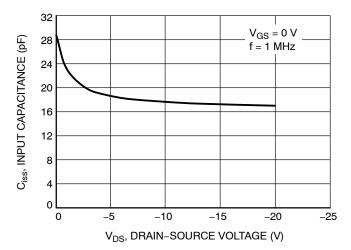


Figure 3. Input Capacitance

<sup>2.</sup> Pulse Test: Pulse Width < 300  $\mu$ s, Duty Cycle  $\leq$  2%.

**MILLIMETERS** 

MIN

0.89

0.01

0.37

0.08

2.80

1.20

1.78

0.30

0.35

2.10

O°

NOM

1.00

0.06

0.44

0.14

2.90

1.30

1.90

0.43

0.54

2.40

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## SOT-23 (TO-236) 2.90x1.30x1.00 1.90P **CASE 318 ISSUE AU**

**DATE 14 AUG 2024** 

MAX

1.11

0.10

0.50

0.20

3.04

1.40

2.04

0.55

0.69

2.64

10°

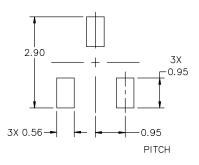




DETAIL "A" Scale 3:1







### NOTES:

DIM

Α

Α1

b

С

D

Ε

е L

L1

HE

Τ

- DIMENSIONING AND TOLERANCING 1. PER ASME Y14.5M, 2018. CONTROLLING DIMENSIONS:
- MILLIMETERS.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE
- BASE MATERIAL.
  DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

## **GENERIC MARKING DIAGRAM\***



XXX = Specific Device Code

= Date Code

= Pb-Free Package

## RECOMMENDED MOUNTING FOOTPRINT

\* For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## **STYLES ON PAGE 2**

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DESCRIPTION:	ON: SOT-23 (TO-236) 2.90x1.30x1.00 1.90P		PAGE 1 OF 2	

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<sup>\*</sup>This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "=", may or may not be present. Some products may not follow the Generic Marking.

## SOT-23 (TO-236) 2.90x1.30x1.00 1.90P CASE 318 ISSUE AU

DATE 14 AUG 2024

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR		NODE D CONNECTION ATHODE	
STYLE 9: PIN 1. ANODE 2. ANODE 3. CATHODE	STYLE 10: PIN 1. DRAIN 2. SOURCE 3. GATE	STYLE 11:         STYLE 12:           PIN 1. ANODE         PIN 1. CA           2. CATHODE         2. CA           3. CATHODE-ANODE         3. AN	ATHODE PIN 1. SOURCE ATHODE 2. DRAIN	STYLE 14: PIN 1. CATHODE 2. GATE 3. ANODE
STYLE 15: PIN 1. GATE 2. CATHODE 3. ANODE	STYLE 16: PIN 1. ANODE 2. CATHODE 3. CATHODE			STYLE 20: PIN 1. CATHODE 2. ANODE 3. GATE
STYLE 21: PIN 1. GATE 2. SOURCE 3. DRAIN	STYLE 22: PIN 1. RETURN 2. OUTPUT 3. INPUT	STYLE 23:         STYLE 24:           PIN 1. ANODE         PIN 1. GAT           2. ANODE         2. DR/           3. CATHODE         3. SOU	TE PIN 1. ANODE AIN 2. CATHODE	STYLE 26: PIN 1. CATHODE 2. ANODE 3. NO CONNECTION
STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE			

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